

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
SANGWOOK PARK	09/29/2011
JONGGI LEE	09/30/2011
WONCHUL LIM	09/30/2011
RECEIVING PARTY DATA	
Name:	Samsung Electronics Co., Ltd
Street Address:	416, Maetan-dong
City:	Yeongtong-gu, Suwon-si, Gyeonggi-do
State/Country:	KOREA, REPUBLIC OF
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	13275074
CORRESPONDENCE DATA	
Fax Number:	(516)692-8889
Phone:	516-692-8888
Email:	mail@chauiplaw.com
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>	
Correspondent Name:	Frank Chau
Address Line 1:	130 Woodbury Road
Address Line 4:	Woodbury, NEW YORK 11797
ATTORNEY DOCKET NUMBER:	8836-733
NAME OF SUBMITTER:	FRANK CHAU
Total Attachments: 2 source=8836-733-Assignment#page1.tif source=SKMBT_50111101716390#page1.tif	

OP \$40.00 13275074

501693535

PATENT
REEL: 027074 FRAME: 0779

ASSIGNMENT

DOCKET NO.: 8836-733 (II-200558-US)

AS A BELOW NAMED INVENTOR, I, and each of us, individually hereby declare that: IN CONSIDERATION of the sum of TEN (\$10.00) dollars or the equivalent thereof, and other good and valuable consideration, the receipt of which from the hereinafter named Assignee is hereby acknowledged, I do hereby sell, assign and forever grant and convey unto:

ASSIGNEE: Samsung Electronics Co., Ltd.

ADDRESS: 416, Maetan-dong, Yeongtong-gu, Suwon-si, Gyeonggi-do, KOREA

Who is my Assignee, and to the successes and assigns of my Assignee, all my right, title and interest, in and for the United States of America and all other countries, including all rights of priority, in and to the invention entitled:

TITLE: SEMICONDUCTOR PACKAGES AND METHODS OF FABRICATING
THE SAME

invented by me (*if only one inventor is named below*) or us (*if more than one inventor is named below*) and described in an application for a United States patent the specification of which is either attached hereto or otherwise accompanies this Assignment or indicates an attorney docket no. 8836-733 (II-200558-US), or is more particularly identified as:

- ☐ executed on even date herewith, or
☐ Serial No. _____ filed in the U.S. Patent & Trademark Office on _____,
or
☐ executed on _____,

and in and to all United States patents which may be granted thereon and therefore, and in and to all certificates of corrections, divisions, continuations, continuations-in-part, reissued and re-examined patents, and to any extensions thereof, said interest being the entire ownership of the patent when granted, to be held and enjoyed by said **SAMSUNG ELECTRONICS CO., LTD.**, my Assignee, its successors, assigns or other legal representatives, to the full end of the term, terms, or any extension or renewal thereof, for which said patent or patents may be granted, as fully and entirely as the same would have been held and enjoyed by me or us if this assignment, sale and conveyance had not been made;

AND I hereby covenant and agree to sign and execute any further documents or instruments which may from time-to-time be either necessary, lawful, proper or requested by the Assignee, in the prosecution of the above-named application or in the preparation and prosecution of any certificate of correction, division, continuation, continuation-in-part, reissue, re-examination, in any amendment, extension, or interference proceeding, whether administrative or judicial, or otherwise, to secure the title hereto in said Assignee;

AND I do hereby authorize and request the Commissioner of Patents and Trademarks to issue said Patent or Patents to the Assignee, and I hereby appoint as my, or our attorney, and authorize and request Frank Chau, Reg. No. 34,136, to insert on this Assignment any further identification or to complete such identification which may be either necessary or desirable in order to comply with the rules of the United States Patent and Trademark Office for recordation of this document.

PATENT

REEL: 027074 FRAME: 0780

I HEREBY DECLARE that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under 1001 of Title 18 U.S. Code and that such willful false statements may jeopardize the validity of the application or any patent issued thereon.

FULL NAME OF FIRST JOINT INVENTOR: Sangwook Park

Citizenship Korea

Inventor's signature: Sangwook Park

Date: 2011. 09. 29

Residence Address: 411-1201, Solbit Maeul SeoheoGrangbl Apt.,
Bansong-dong, Hwaseong-si, Gyeonggi-do, Republic of Korea

Mailing Address: Intellectual Property Team, Samsung Semiconductor,
Samsung Electronics Co., Ltd. San #16, Banwol-dong,
Hwasung-si, Gyeonggi-do, Republic of Korea, #445-701

FULL NAME OF SECOND JOINT INVENTOR: Jonggi Lee

Citizenship Korea

Inventor's signature: Jonggi Lee

Date: 2011. 09. 30

Residence Address: 1205-901, Hosu Maeul Dongbo Nobility Apt.,
Dongbaek-dong, Giheung-gu, Yongin-si, Gyeonggi-do,
Republic of Korea

Mailing Address: Intellectual Property Team, Samsung Semiconductor,
Samsung Electronics Co., Ltd. San #16, Banwol-dong,
Hwasung-si, Gyeonggi-do, Republic of Korea, #445-701

FULL NAME OF THIRD JOINT INVENTOR: Wonchul Lim

Citizenship Korea

Inventor's signature: Wonchul Lim

Date: 2011. 09. 30

Residence Address: 106-1104, Lotte Castle Apt., Buksu-ri, Baebang-eup,
Asan-si, Chungcheongnam-do, Republic of Korea

Mailing Address: Intellectual Property Team, Samsung Semiconductor,
Samsung Electronics Co., Ltd. San #16, Banwol-dong,
Hwasung-si, Gyeonggi-do, Republic of Korea, #445-701

